Nanomanufacturing University of Michigan ME599-002 | Winter 2010



17: Purification, functionalization, and separation of nanostructures

March 24, 2010

John Hart

<u>ajohnh@umich.edu</u> http://www.umich.edu/~ajohnh

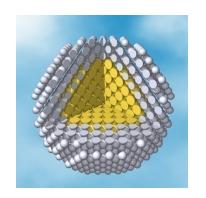
Announcements

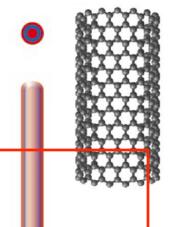
- Project proposals due no later than Friday
 - Please give me printed copy, and register at http://bit.ly/9RWIEx
- Peer review on project proposals instead of video review
 - Due Fri Apr/2, but please do asap
 - Honor system, 5 reviews per person and per proposal
 - 2.5% grade (0.5% per review), no credit if late
 - Review sheet and updated project description to be posted later today
- PSET4 will be (relatively) brief, and will be a team assignment, due M Apr/12
- Project is 50% of course grade!
 - Start now and make a schedule
 - Don't get hung up on ideas
 - Divide and conquer
 - Meetings to be scheduled late next week

Nanomanufacturing: our mission

- Understand the fundamental properties of nanostructures, e.g., nanoparticles, nanotubes, and nanowires
- Understand how nanostructures interact with one another and their surroundings
- Understand how to make and assemble nanostructures; how to control their size, structure, and placement
- Understand how the properties of nanostructures scale based on their assembly and interactions
- Combine our knowledge to design new devices, materials, and manufacturing processes







7 lectures to go



IV: A	ssembly of nanos	structures; property scaling	
18	Mar/24 (W)		
	Mar/26 (F)	-	
19	Mar/29 (M)	Self-assembly of micelles and block copolymers	
20	Mar/31 (W)	Monolayer and layer-by-layer assembly	
21	Apr/5 (M)	Self-assembly using capillary forces	
22	Apr/7 (W)	Self-assembly using applied fields and biomolecular	
		interactions	
23	Apr/12 (M)	Manipulation and joining methods	
25	Apr/14 (W)	Percolation and network properties	
	Apr/16 (F)	-	
26	Apr/19 (M)	No class; project presentations in the evening	
	Apr/20 (Tu)	Final report due by 5PM	
	Apr/28 (W)	GCC examination, 10.30a-1.30p	

What comes after bulk synthesis of nanostructures?



Purification

- Remove impurities such as undesired byproducts, unreacted catalyst
- Anneal to improve crystallinity
- Etch to control size

Stabilization and functionalization

 Attach/associate molecules with nanomaterial surfaces to facilitate interaction with other materials and phases

Separation/sorting

Partition elements by size, shape, and/or electronic structure



- Process order is generally interchangeable based on application; however, it's useful to have structures isolated (dispersed) in solution before etching or sorting
- Functionalization is often a means of
 - dispersion (exfoliation/isolation), and
 - interfacing structures to one another, or to other materials

Today's readings

Nominal: (ctools)

- Athakul et al., "Size fractionation of metal nanoparticles by membrane filtration"
- Arnold et al., "Sorting carbon nanotubes by electronic structure using density differentiation"
- Ho et al., "Free flow electrophoresis for separation of CdTe nanoparticles"

For reference: (ctools)

- Hirsch, "Functionalization of single-walled carbon nanotubes"
- Sharma et al., "Shape separation of gold nanorods using centrifugation"
- Williams, "Etch rates for micromachining processing"



Large-scale CNT manufacturing



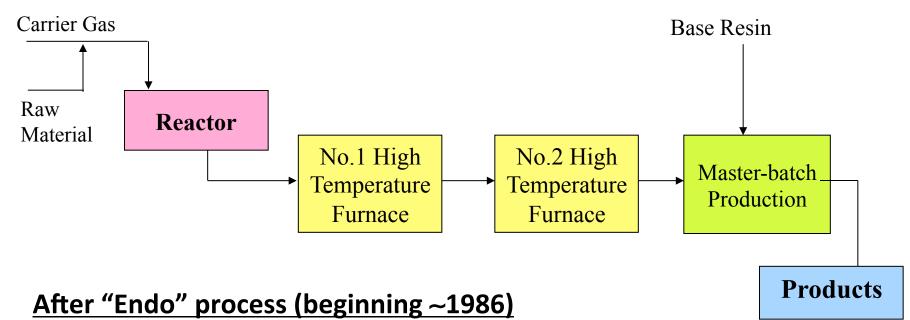




only 100g! (courtesy NCT Japan)

Large scale CNT manufacturing process: growth, annealing, mixing

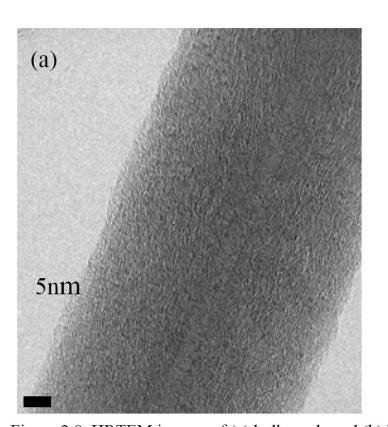




- > Floating catalyst CVD
- Followed by two stages of high temperature treatment
- \triangleright Now > 300 tons/yr
- ➤ High purity: 99.5 wt% as carbon
- >CNT diameter 40-90 nm

High-temperature annealing of CNTs

- Heals defects by atomic rearrangement
- Also evaporates catalyst
- See also "welding" by ion/electron beams (later)



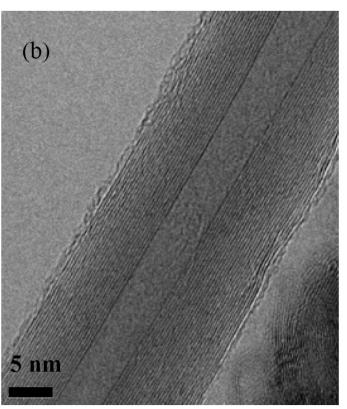


Figure 2.8. HRTEM images of (a) bulk grade and (b) high purity grade MWCNTs (Courtesy of NCT).

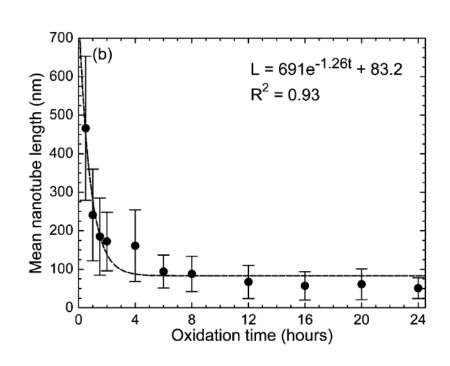


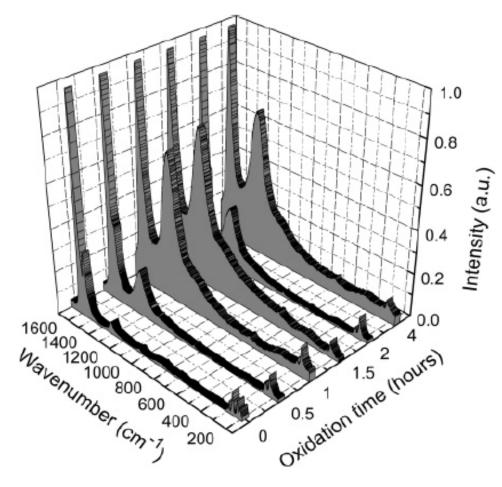
Purification: chemical etching

- Largely similar to "microfabrication etching", just be especially aware of geometry- and crystal-sensitive etch rates
- Some bulk-nano differences are driven by electronic structure
- Consider role of defects in propagating breakage or fastetch directions \rightarrow much more important for nanostructures than for thin films!

Example: acid purification (etching) of CNTs

- Mixture of HNO₃, H₂SO₄
- Cuts CNTs at defect sites →
 exponential length decay
- Acid can also remove catalyst





Example: acid purification (etching) of CNTs



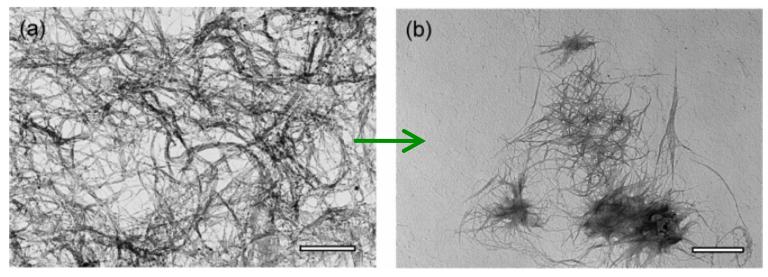
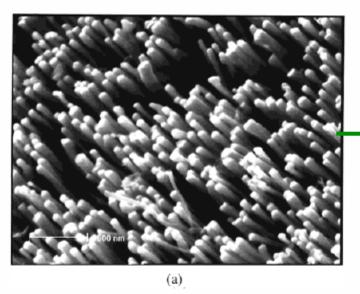


Figure 3. Pristine nanotubes (a) and tubes oxidized for 2 h and treated with Piranha solution to remove amorphous carbon (b). Scale bars = 500 nm.

Structural selectivity: opening CNT caps by plasma/oxygen etching





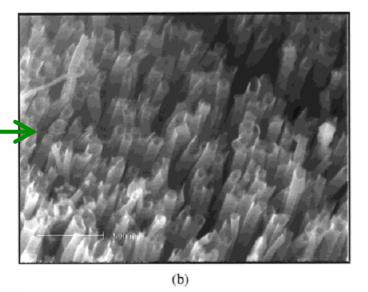
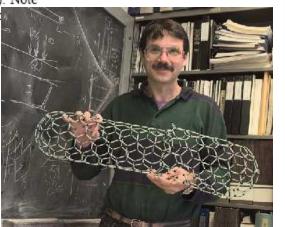
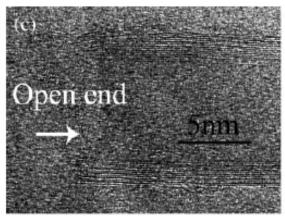


Figure 3. SEM images of the aligned nanotubes (a) before and (b) after the plasma-treatment for 80 min, followed by a gentle wash with HCl (37%) to remove the Fe catalyst residues, if any (see text). Note that the micrographs shown in (a) and (b) were not taken fro same spot due to technical difficulties.

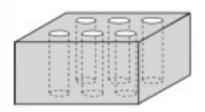




Prof. Alex Zettl, Berkeley

Plasma etching to expose NWs grown within a membrane template





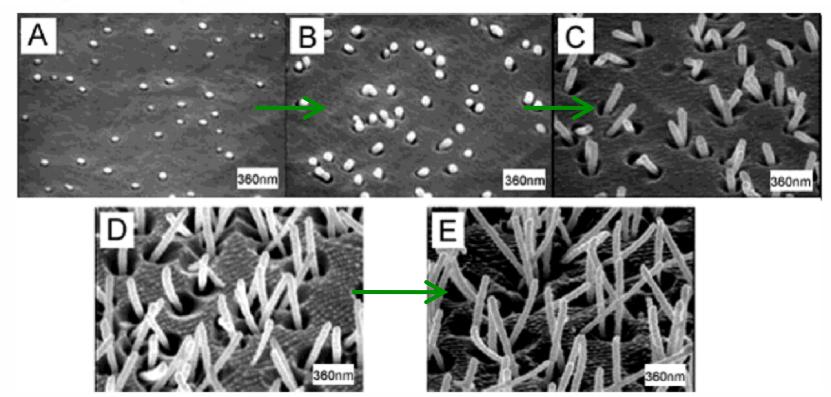


Figure 3. FESEMs of the surfaces of membranes that were O2-plasma etched for 5 (A), 10 (B), 30 (C), 60 (D) and 120 (E) seconds.

Etchants ("Williams chart")



Etchant	Etchant Abbrev.	Target Material
Isotropic Silicon Etchant "Trilogy Etch" (126 HNO ₃ : 60 H ₂ O: 5 NH ₄ F), ~20°C	Si Iso Etch	Silicon
KOH (30% by weight), 80°C	кон	Silicon ODE
10:1 HF (10 H ₂ O : 1 49% HF), ~20°C	10:1 HF	Silicon Dioxide
5:1 BHF (5 40% NH₄F : 1 49% HF), ~20°C	5:1 BHF	Silicon Dioxide
Pad Etch 4 from Ashland (13% NH ₄ F + 32% HAc + 49% H ₂ O + 6% propylene glycol + surfactant), ~20°C	Pad Etch 4	SiO ₂ , not Al
Phosphoric Acid (85% by weight), 160°C	Phosphoric	Silicon nitride
Al Etchant Type A from Transene (80% H ₃ PO ₄ + 5% HNO ₃ + 5% HAc +10%H ₂ O), 50°C	Al Etch A	Aluminum
Titanium wet etchant (20 H ₂ O : 1 H ₂ O ₂ : 1 HF), ~20°C	Ti Etch	Titanium
Chromium etchant CR-7 from Cyantek (9% (NH ₄) ₂ Ce(NO ₃) ₆) + 6% HClO ₄ + H ₂ O), ~20°C	CR-7	Chromium
Chromium etchant CR-14 from Cyantek (22% (NH4)₂Ce(NO3)₅) + 8% HAc+ H2O), ~20°C	CR-14	Chromium
Molybdenum etchant (180 H ₃ PO ₄ : 11 HAc : 11 HNO ₃ : 150 H ₂ O), ~20°C	Moly Etch	Molybdenum
Hydrogen peroxide (30wt% H₂O₂, 70wt% H₂O), 50°C	H ₂ O ₂ 50ºC	Tungsten
Copper etchant type CE-200 from Transene (30% FeCl ₃ + 3-4% HCl + H ₂ O), ~20°C	Cu FeCl ₃ 200	Copper
Copper etchant APS 100 from Transene (15-20% (NH ₄) ₂ S ₂ O ₈ + H ₂ O), 30°C	Cu APS 100	Copper
Dilute aqua regia (3 HCI: 1 HNO ₃ : 2 H ₂ O), ~30°C	Dil. Aqua regia	Noble metals

Gold etchant AU-5 from Cyantek (5% I ₂ +10% KI + 85% H ₂ O), ~20°C	AU-5	Gold
Nichrome etchant TFN from Transene (10-20% (NH ₄) ₂ Ce(NO ₃) ₆) + 5-6% HNO ₃ + H ₂ O), \sim 20°C	NiCr TFN	NiCr
1 H ₂ SO ₄ : 1 H ₃ PO ₄ , 160°C	Phos+Sulf	Sapphire
Piranha (~50 H ₂ SO4 : 1 H ₂ O ₂), 120°C	Piranha	Cleaning
Microstrip 2001 photoresist stripper, 85°C	Microstrip	Photoresist
Acetone, ~20°C	Acetone	Photoresist
Methanol, ~20°C	Methanol	Cleaning
Isopropanol, ~20°C	IPA	Cleaning
XeF ₂ , 2.6 mTorr, homemade chamber	XeF ₂	Silicon
HF + H₂O vapor, 1 cm over dish with 49% HF	HF vapor	Silicon dioxide
Technics plasma, O ₂ , 400 W @ 30 kHz, 300 mTorr	Technics O ₂	Photoresist
STS ASE DRIE, mechanical chuck, high frequency, typical recipe	DRIE HF mech.	Silicon
STS ASE DRIE, electrostatic chuck, high frequency, typical recipe	DRIE HF ES	Silicon
STS ASE DRIE, mechanical chuck, stop-on-oxide (low-frequency platen), typical recipe	DRIE LF mech.	Silicon
STS ASE DRIE, electrostatic chuck, stop-on-oxide (low-frequency platen), typical recipe	DRIE LF ES	Silicon
STS 320 RIE, SF ₆ , 100 W @ 13.56 MHz, 20 mTorr	STS 320 SF ₆	Si, SiN, metals
STS 320 RIE, SF ₆ + O ₂ , 100 W @ 13.56 MHz, 20 mTorr	STS SF ₆ +O ₂	Si, SiN, metals
STS 320 RIE, CF ₄ , 100 W @ 13.56 MHz, 60 mTorr	STS 320 CF₄	Si, SiO, SiN
STS 320 RIE, CF ₄ + O ₂ , 100 W @ 13.56 MHz, 60 mTorr	STS CF ₄ +O ₂	Si, SiO, SiN
lon milling with argon ions at 500 V, ~1 mA/cm², normal incidence (Commonwealth data)	lon Mill	Everything

Notation:

BHF = buffered hydrofluoric acid

DRIE = deep reactive ion etch

RIE = reactive ion etch

STS ASE = Surface Technology Systems Advanced Silicon Etch

Catalytic etching of graphene



Purification: chemical etching

- Etch types
 - Wet
 - Dry
- What will etch?
 - Organics
 - Semiconductors
 - Oxides
 - Metals
- Considerations
 - Etch rate
 - Selectivity (e.g., rate_A/rate_B)
 - Compatibility with other materials in your process
 - Drying process (aggregation and capillary forces)



Dispersion vs. solution



Dispersion



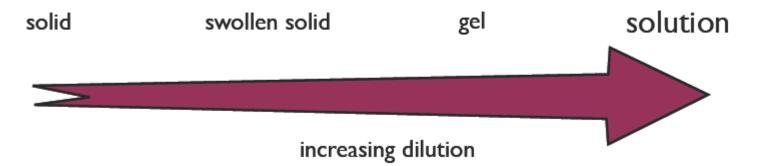
- Heterogeneous (mixture)
- Metastable
- does NOT form spontaneously (Think of a mayonnaise)

need for stirring, shearing, sonicating....



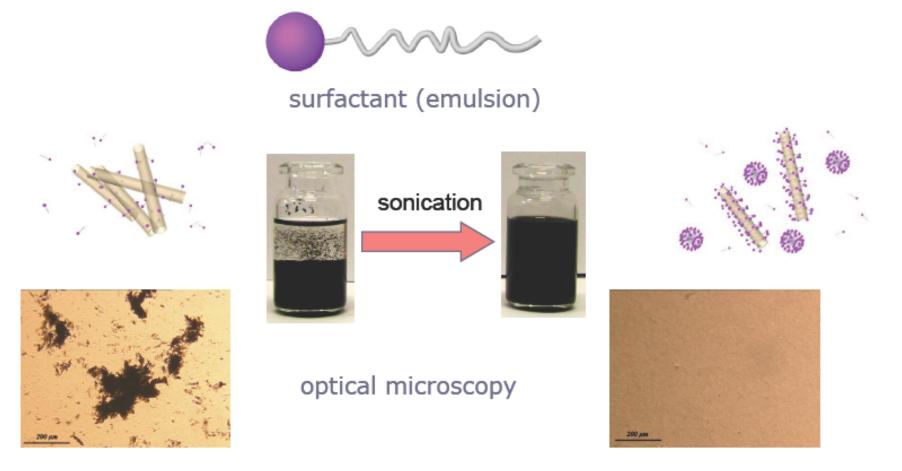


- Homogeneous
- Stable
- Solution forms spontaneously (think of salt or sugar in water)



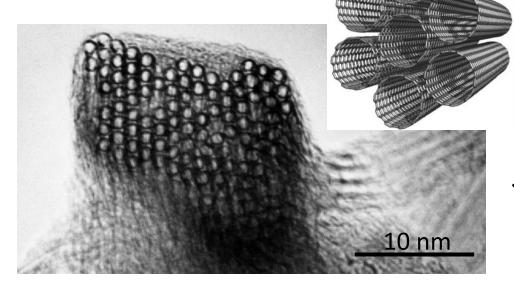
Basic dispersion of CNTs in H₂O





e.g., <0.1 wt% CNTs in 1% SDS (sodium dodecyl sulfate) in DI-H₂O





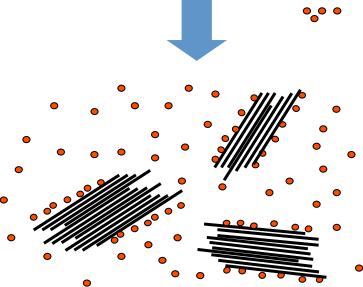




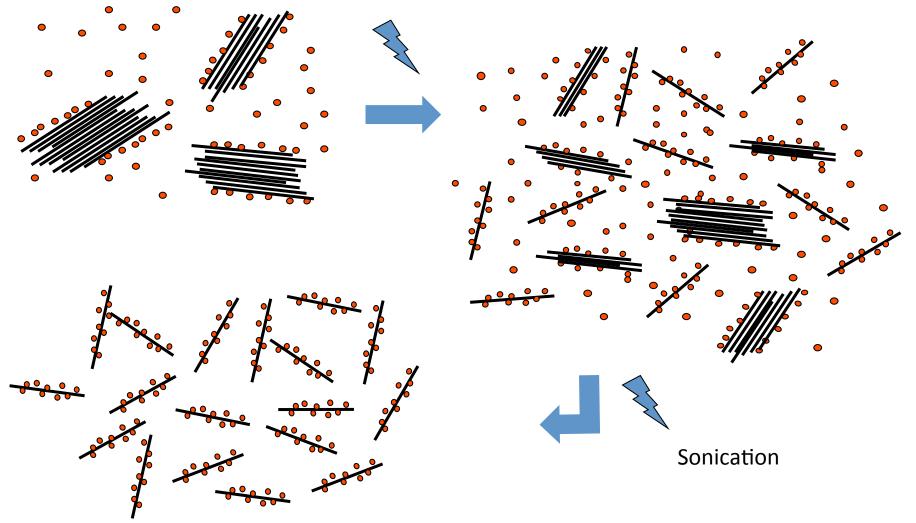


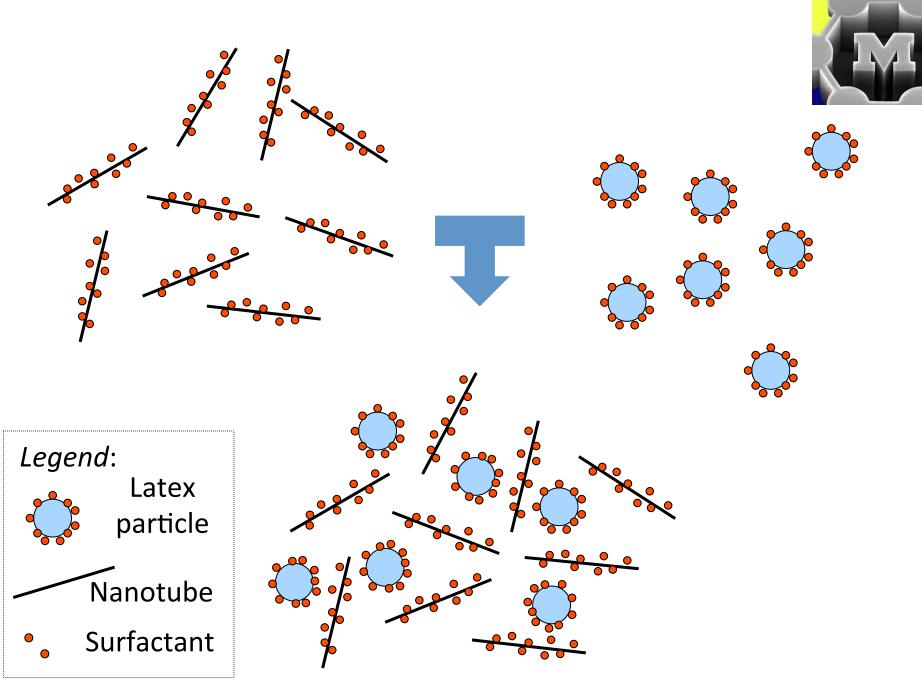


Surfactant molecules









Horn sonicator





Monitoring exfoliation of CNTs



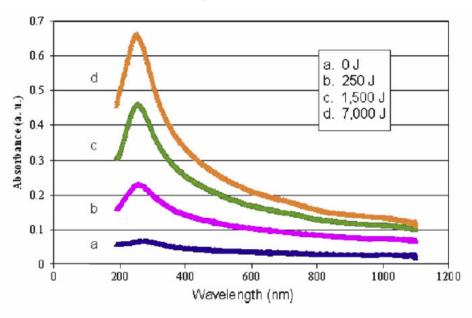


Fig. 1. Evolution of the UV spectra of Carbolex NT solution as function of the energy delivered. Carbolex solution 0.5 wt% (diluted 750 times; continuous power of sonication of 20 W). The absorbance increases continuously with increasing energy-input.

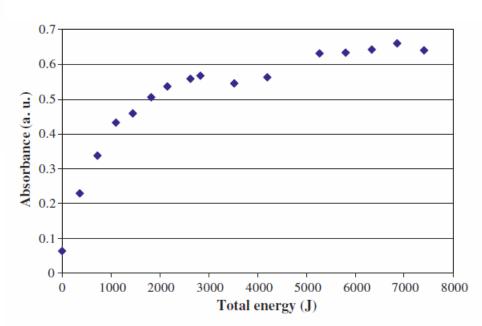
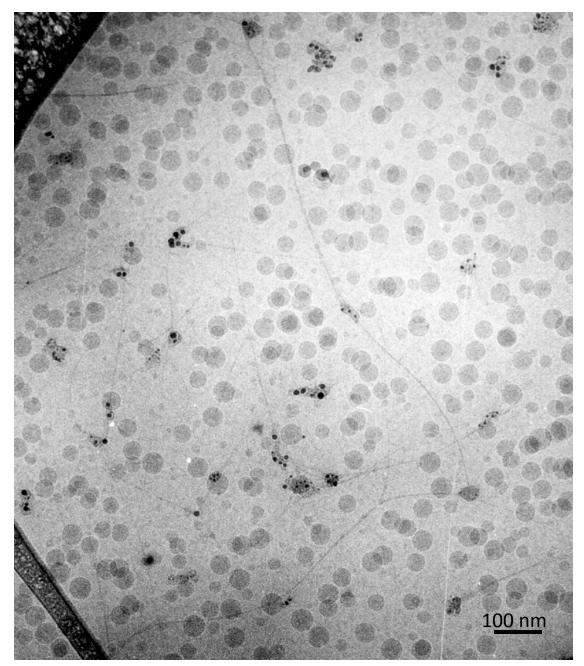


Fig. 2. Evolution of the height of the peak located around 250 nm for an aqueous 0.5 wt% Carbolex NT solution (diluted 750 times).



Step 2:

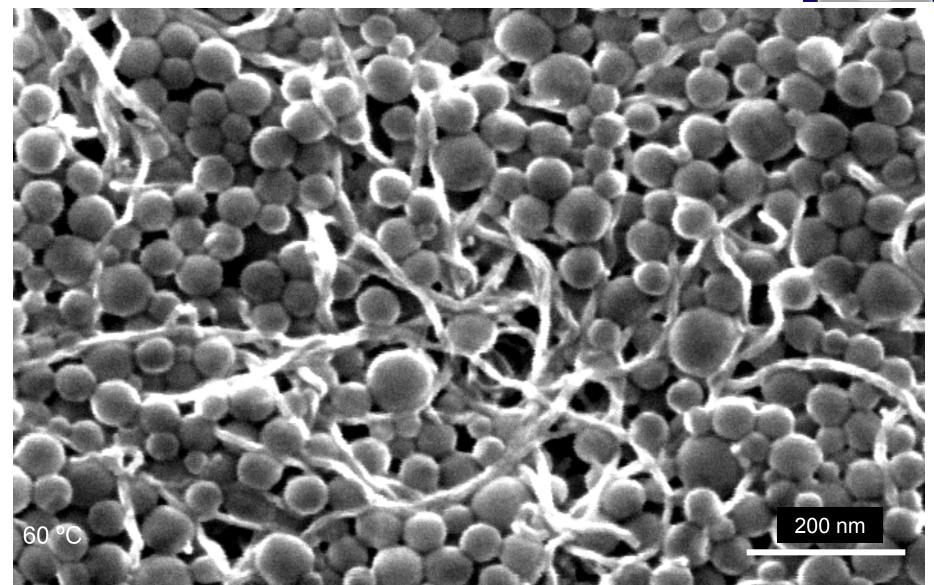
NTs mixed with a polymer latex



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Step 3: Freeze-drying of the mixture

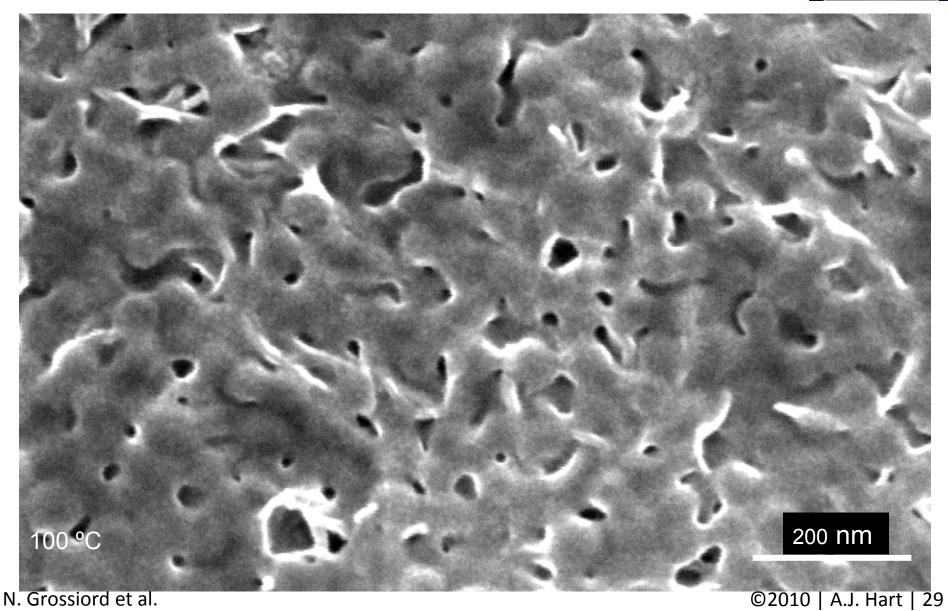




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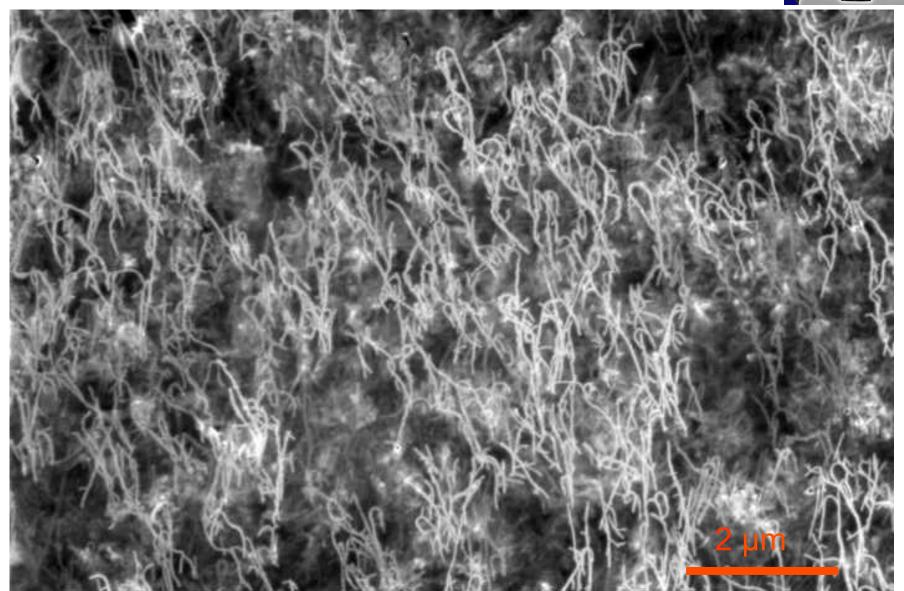
Step 4: Compression Molding



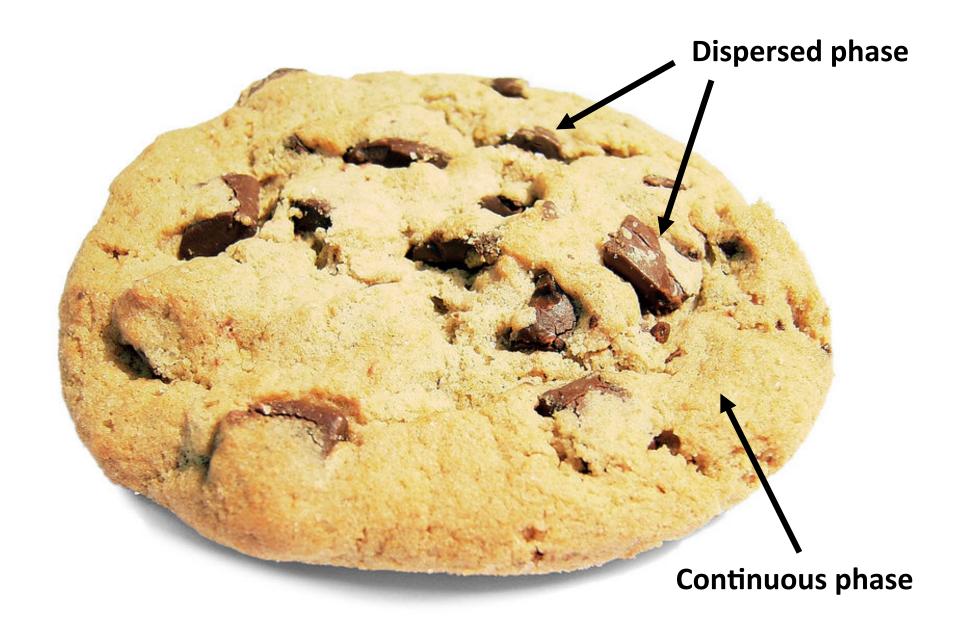


Final product: Nanocomposite film



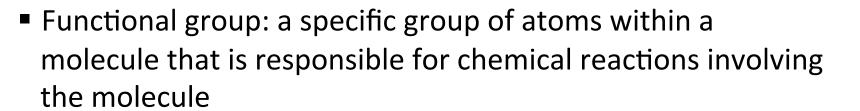


N. Grossiord et al.



Functionalization: approaches

- Covalent bonding
- Non-covalent association (e.g., polymer wrapping)
- Ionic (charge) stabilization



Initially associated molecules can be a template for secondary bonding to desired outer functional groups → functionalization "platforms"



Where do functional groups attach?



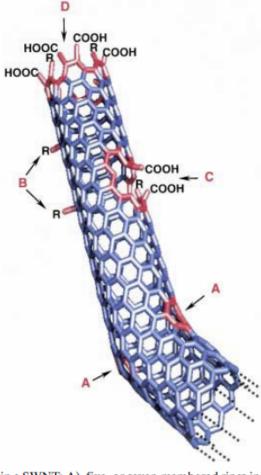


Figure 3. Typical defects in a SWNT: A) five- or seven-membered rings in the C framework, instead of the normal six-membered ring, leads to a bend in the tube, B) sp³-hybridized defects (R = H and OH), C) C framework damaged by oxidative conditions, which leaves a hole lined with -COOH groups, and D) open end of the SWNT, terminated with -COOH groups. Besides carboxy termini, the existence of which has been unambigously demonstrated, other terminal groups such as -NO2, OH, H, and =O are possible.

Some functionalization typically native after growth, e.g., -COOH at ends



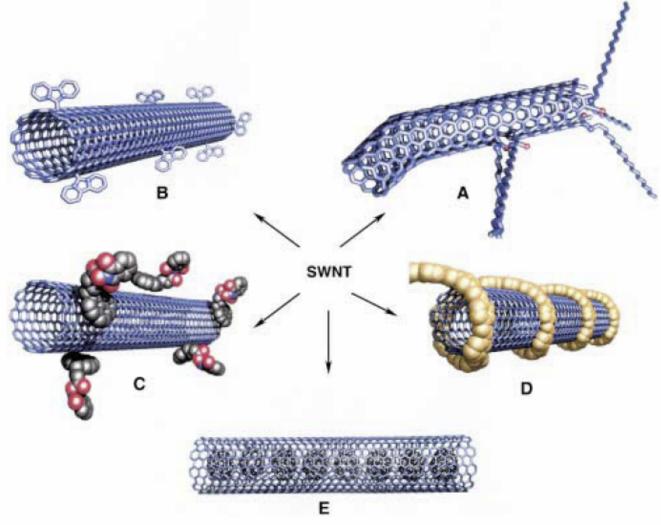
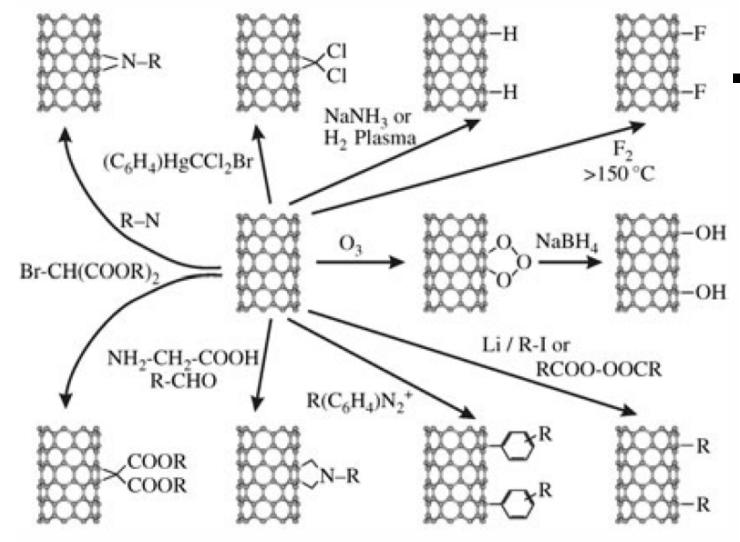


Figure 5. Functionalization possibilities for SWNTs: A) defect-group functionalization, B) covalent sidewall functionalization, C) noncovalent exohedral functionalization with surfactants, D) noncovalent exohedral functionalization with polymers, and E) endohedral functionalization with, for example, C_{60} . For methods B-E, the tubes are drawn in idealized fashion, but defects are found in real situations.

Example: CNT sidewall functionalization





Smaller diameter = easier to substitute

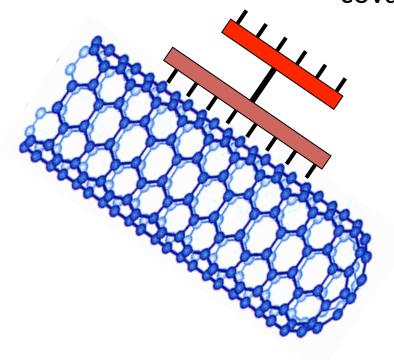
Figure 6. Overview of possible addition reactions for the functionalization of the nanotube sidewall.

Functionalization as a platform



Two levels

- van der Waals (non-covalent)
- covalent



Application: composites for sporting goods





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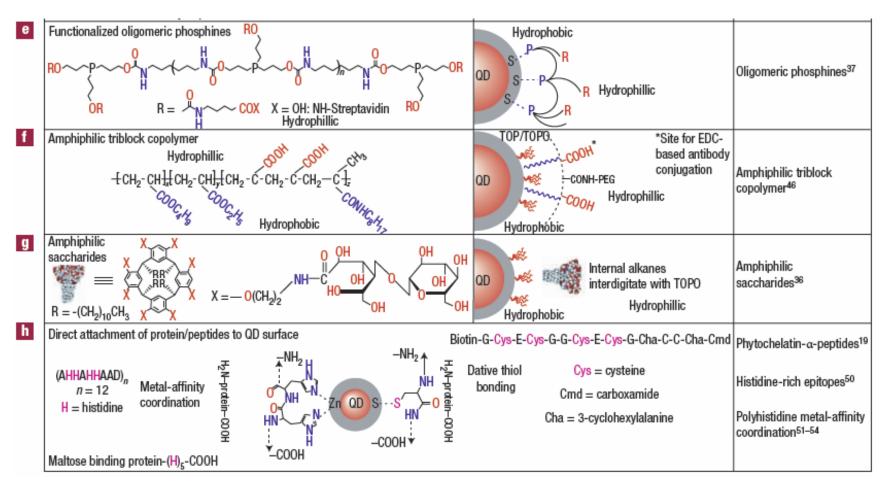
Functionalization of semiconductor NPs



	Representative surface-capping strategies	Mechanism of interactoin	Examples
а	Monothiolated caps $n=1$: mercaptoacetic acid $n=2,10,15$, benzyl Hydrophillic HS(CH ₂) ₁₁ (OCH ₂ CH ₂) ₄ OR R= -H, -CH ₂ COOH	Dative thiol bond	Mercaptocarbonic acids ^{4,39} Alkylthiol terminated DNA ⁴¹ Thioalkylated oligo-ethyleneglycols ³²
b	Bidentate thiols $R = {-OH \over -(OCH_2CH_2)_nOH} = 3,5,\sim 12$ SH SH	Two interactions/ligand	Dihydrolipoic acid derivatives ^{26,43}
C	Silane shell or box dendrimer Hydrophobic Hydrophillic Hydrophobic Hydrophillic $HS \longrightarrow Si-O-Si-R$ $HS \longrightarrow NOONOH$ $NOOH$ N	OSi SS —SiOSiR OSi	Mercaptopropyl silanols ^{3,40} Amine box dendrimers ³¹
d	Hydrophobic interactions $\begin{array}{c} \text{CH}_3(\text{CH}_2)_{16} & \text{O} & \text{H} \\ \text{CH}_3(\text{CH}_2)_{16} & \text{O} & \text{H} \\ \text{CH}_3(\text{CH}_2)_{16} & \text{O} & \text{CH}_3(\text{CH}_2)_{45} \\ \text{OCH}_3(\text{CH}_2)_7 & \text{NHCO} & \text{COOH} \\ \text{CH}_3(\text{CH}_2)_7 & \text{NHCO} & \text{COOH} \\ \text{Hydrophobic} & \text{Hydrophillic} \end{array}$	Hydrophobic Hydrophillic Si - P NHCO CONH-R NHCO CONH-R COOH TOP/TOPO	Phosphatidylethanol amine Phosphatidycholine micelles ³³ Modified acrylic acid polymer ^{33,44,45} Poly(maleic anhydride) alt-1-tetradecene ⁶⁵

Functionalization of semiconductor NPs





Functionalization of metal oxide NPs

Ligand	Name	Reacting surfaces	References
R-SH R-S-S-R'	thiols disulfides	Au, Ag, Cu, Hg, Fe	3-5, 112-115
о R—С—ОН	carboxylic acids	metal oxides	25, 26, 33, 35, 97, 98
OH R—P—OH O	phosphonates phosphonic acids	metal oxides	6-8, 49, 99-102
0-R' R-Si-0-R' 0-R'	siloxanes	metal oxides	32, 43, 80-87, 89-96
R C=C OH	enediols	transition metal oxides (TiO ₂ , Fe ₂ O ₃ , ZrO)	3, 34, 103-109
HO—CH ₂ R	diols	Fe ₂ O ₃	110, 111



-R = alkyl group C_nH_{2n+1}

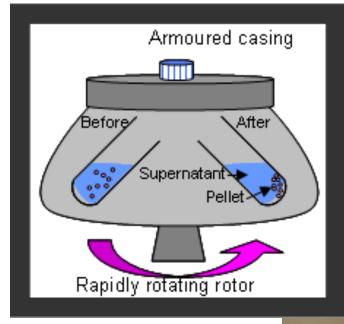
Separation and sorting: methods

- Centrifugation
- Electrophoresis → when we discuss external fields later
- Filtering, size exclusion

Overarching principle: create and amplify a difference in mobility of nanostructures in a fluid based on their size, shape, and/or surface charge

Centrifuge

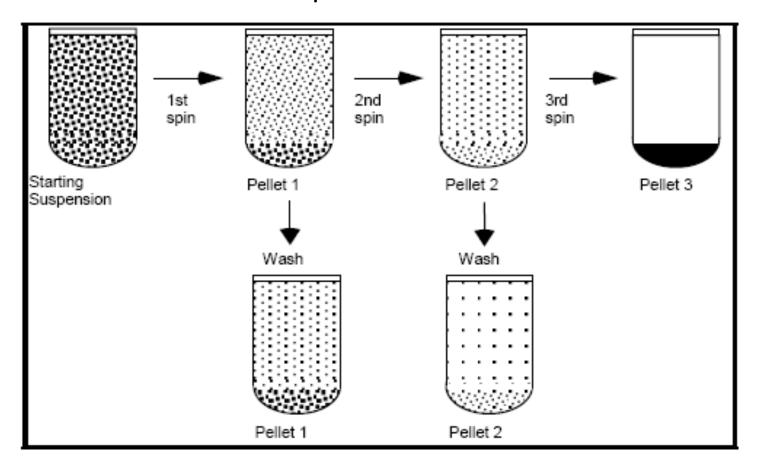






Differential centrifugation

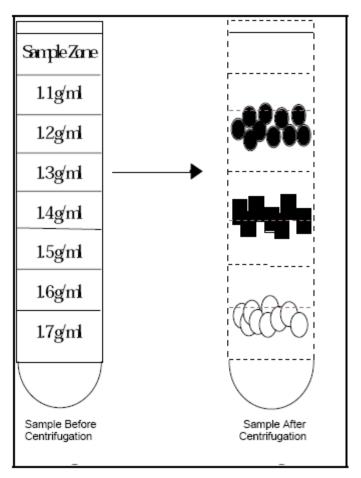
- Spin a solution (or suspension) in a uniform density solution
- Larger particles sediment faster (earlier steps shown below), and at lower speeds
- Wash sediment between steps to remove contaminants



Density gradient centrifugation

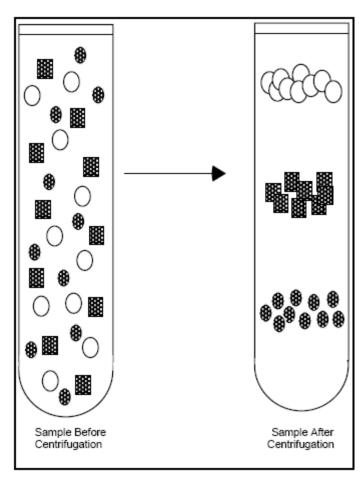


rate-zonal (size, mass)



Useful if mass differs but density does not If centrifuge too long, all particles settle

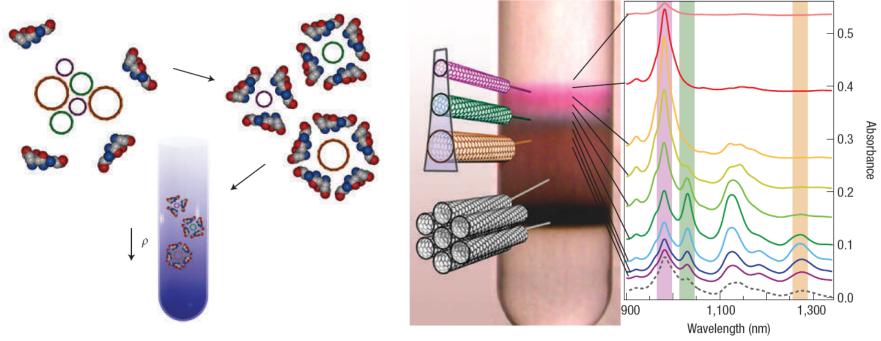
isopycnic (density)



Reaches equilibrium

CNT separation using density gradients

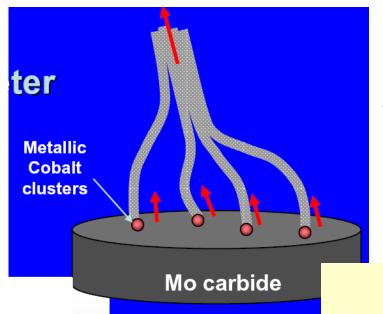


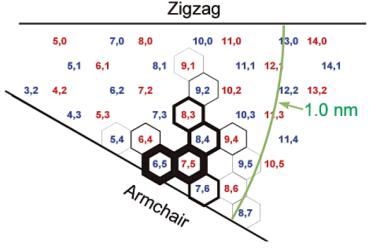


- Disperse CNTs in surfactant mix: competing surfactants adsorb based on CNT electronic structure
- Ultracentrifuge (\approx 50,000 rpm, \approx 12h) in a density gradient and repeat
- Separation > 97% within 0.02nm diameter
- Differentiate metal/semiconducting as well

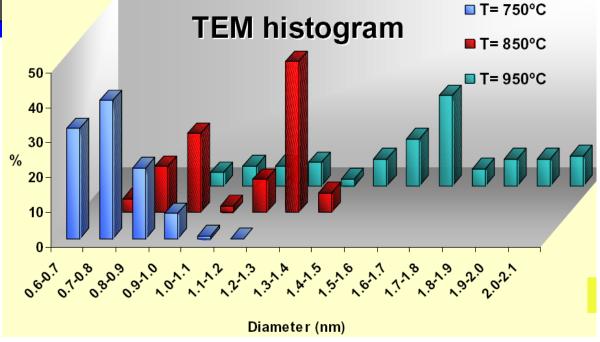
CoMoCat CNT growth process







CNT diameter increases with % reaction temperature



Characterization: photoluminescence



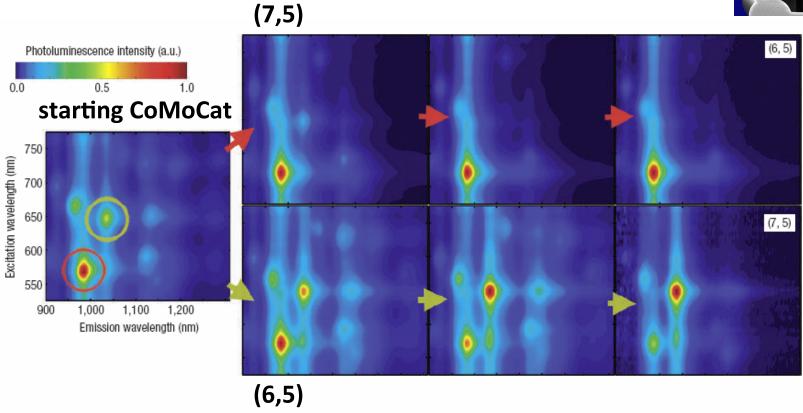
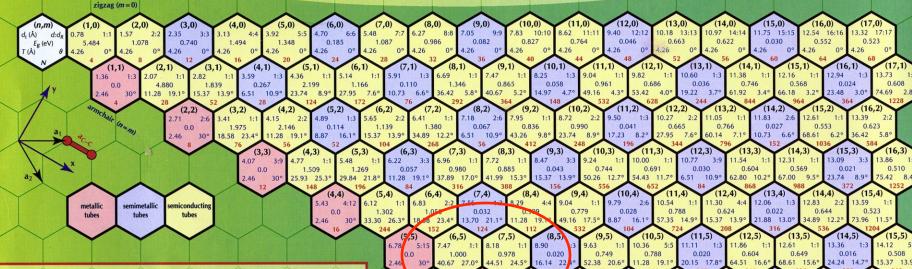


Figure 2 Refinement by repeated centrifugation in density gradients. By successively separating SC-encapsulated SWNTs, the isolation of specific, targeted chiralities improves. Plotted are photoluminescence intensities as a function of excitation and emission wavelengths. Here, the isolation of the (6,5) and (7,5) chiralities (circled red and green in the left-most plot) of SWNTs grown by the CoMoCAT-method before sorting, is improved (in the top and bottom panels, respectively) by successively repeating density gradient centrifugation for three iterations (from left to right). After three iterations of enriching the (6,5) chirality (7.6 Å), a narrow diameter distribution is achieved in which >97% of semiconducting SWNTs are within 0.2 Å of the mean diameter. Alternatively, refined isolation of the (7,5) chirality can be realized (bottom). In this case, after three iterations of sorting, the (7,5) chirality (8.3 Å), initially substantially less concentrated than the (6,5) chirality, becomes dominant. Further improvements may be possible with additional centrifugation cycles.

Periodic Table of Carbon Nanotubes



The semi-empirical bandgap E_0 is calculated according to H. Yorikawa and S. Muramatsu, Phys. Rev. B **52**, 2723 (1995) for the semiconducting tubes (no curvature effects) and A. Kleiner and S. Eggert, Phys. Rev. B **63**, 073408 (2001) for the metallic and semi-metallic tubes (includes curvature). All other val

carbon-carbon distance ac-c length of unit vector unit vectors a1, a2 reciprocal unit vectors chiral vector circumference of tube diameter of tube chiral angle highest common divisor of (n, m)highest common divisor of d_R (2n+m,2m+n)T translational vector of 1D unit cell length of T

number of atoms per 1D unit cell

N

18.58 23.4° 13.70 21.1° 11.28 19.1° 4
152 124 (7,5) 112 (8,5)
5:15 7.47 1:1 8.18 1:1 8.90
0 1.000 0.978 0.020
1.000 40.67 27.0° 44.51 24.5° 16.14 2
0 364 (6,6) (7,6)
8.14 6:18 8.83 1:1 9

11.28 19.19 18.0° 37.89 0.646 0.564 0.011 0.553 70.95 21.4 11.28 19.1 13.66 14.38 0.545 0.552 18.58 23.4° 78.26 22.2 15.01 0.005 0.498 70.18 28.39 25.93 25.39 81.67 24.0°

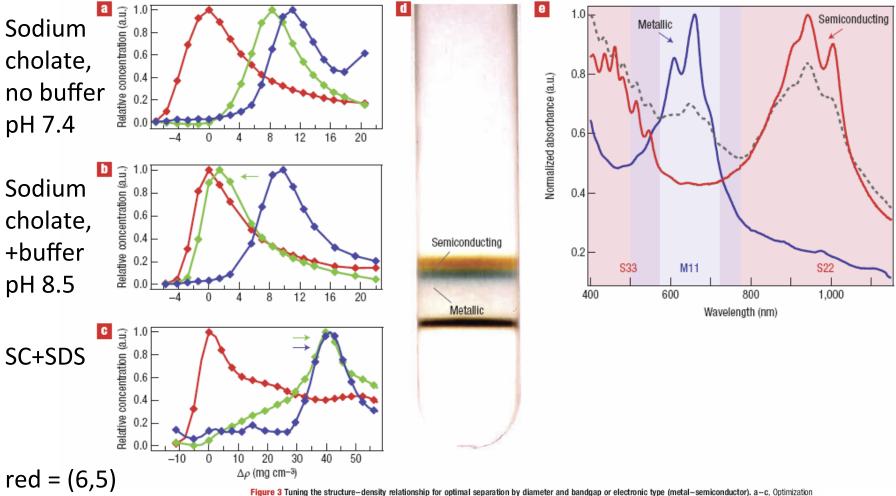
0.014

(10,10) (11,10) (12,10) 13.57 10:30 14.25 1:1 14.95 2:2 0.507 2.46 30° 77.56 28.4° 40.67 27.0° 1324 (11,11) (12,11) 14.93 11:33 15:61 1:1 0.0 (0.48) 84.94 28.6° (10,11)



Tuning selectivity by surfactant mixture



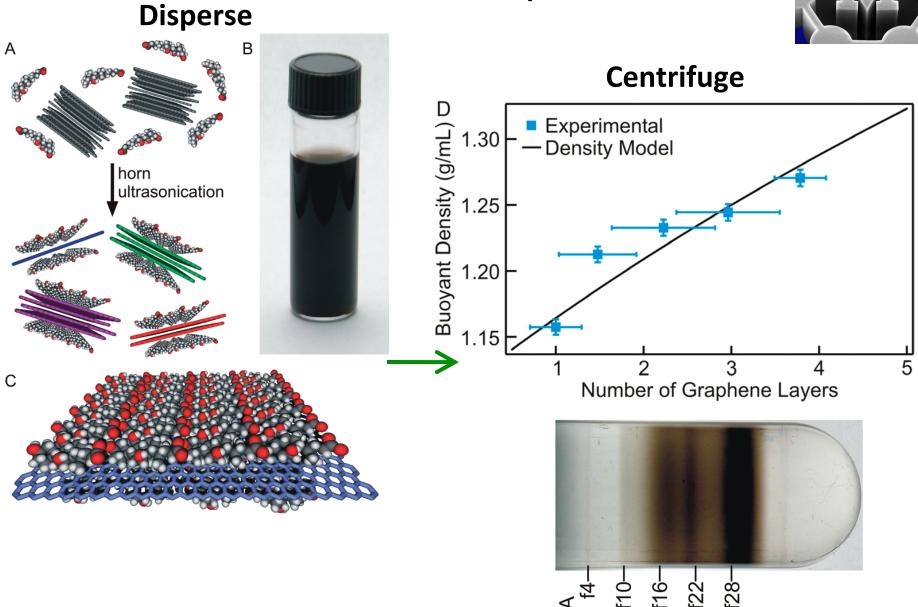


red = (6,5) green = (7,5) blue = (9,5) and (8,7)

Figure 3 Tuning the structure—density relationship for optimal separation by diameter and bandgap or electronic type (metal—semiconductor). a—c, Optimization of separation by diameter and bandgap. The concentration of the (6,5), (7,5) and (9,5)/(8,7) chiralities of CoMoCAT-grown SWNTs (coloured red, green and blue; diameters (ref. 5) of 7.6, 8.3 and 9.8/10.3 Å, respectively) are plotted against $\Delta\rho$. Concentrations were determined from absorbance spectra (Fig. 1c and Supplementary Fig. S1). The encapsulation agents and conditions were SC, no buffer, pH 7.4 (a), SC, 20 mM Tris buffer, pH 8.5, enhanced isolation of the larger diameter SWNTs, (9,5)/(8,7) (b), SC with the addition of SDS as a co-surfactant (1:4 ratio by weight, SDS/SC), enhanced isolation of the smaller diameter SWNTs, (6,5), pH 7.4 (c). ρ for the fractions with the highest (6,5) chirality relative concentration in a—c are all 1.08 \pm 0.02 g cm⁻³. Arrows mark shifts with respect to a. d,e, Optimization of separation by electronic type. d, Photograph of laser-ablation-grown SWNTs separated in a co-surfactant solution (1:4 SDS/SC). The top band (orange) corresponds to predominantly semiconducting SWNTs (absorbance spectra plotted in red in e) and the band just below it (green) is highly enriched in metallic SWNTs, although some semiconducting SWNTs remain (absorbance spectra plotted in Supplementary Fig. S6). $\Delta\rho$ between the two bands and ρ for the top band are 0.006 g cm⁻³ and 1.12 \pm 0.02 g cm⁻³, respectively. Further tuning of the structure—density relationship (3:2 ratio by weight SDS/SC) results in the isolation of predominantly metallic SWNTs (absorbance spectra plotted in blue in e; heterogeneous mixture before sorting plotted with a dashed grey line). (S33, M11, S22 highlighted as in Fig. 1g.)

Separation of graphene by N_{layers}





Shape separation of Au nanostructures



Start

100nm

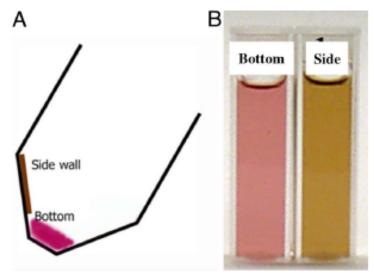
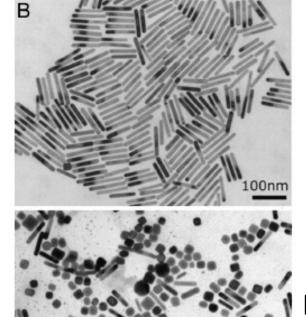


Fig. 3. Separated Au nanoparticles. (A) Schematic drawing of a centrifuge tube after the centrifugation and the color of resulting solutions. (B) The color of the solution taken from 2 different locations shown in A.



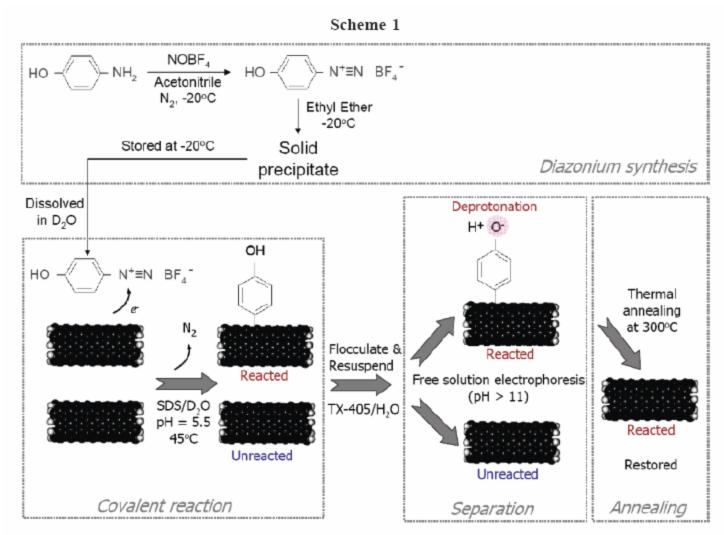
Bottom

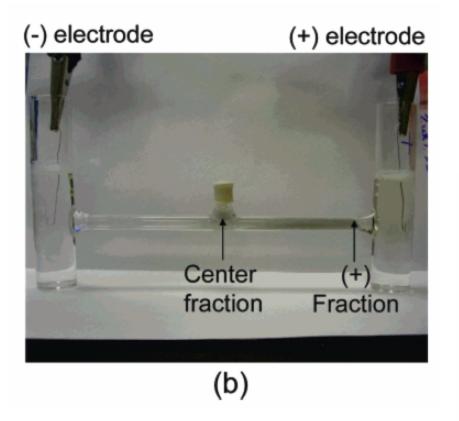
Sidewall

100nm

CNT separation by functionalization then electrophoresis









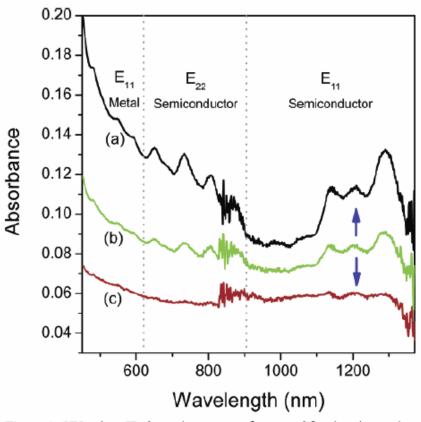


Figure 4. UV—vis—nIR absorption spectra of separated fractions in reaction 1: (a) center fraction, (b) original sample, and (c) (+) fraction.

Membrane filtration



Membrane

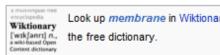
From Wikipedia, the free encyclopedia

In medicine, microbiology, cellular physiology and biochemistry a **membrane** is a thin layer that separates various cellular structures or organs. It usually includes lipid bilayer reinforced by proteins and other macromolecules, and can refer to:

- Basement membrane, the combination of the basal lamina and lamina reticularis or of two basal laminae
- Biological membrane
 - Cell membrane
 - Endomembrane system that divides the cell into organelles
 - Outer membrane or inner membrane of an organelle
 - S-layer, a cell membrane of bacteria
- Mucous membrane
- Serous membrane and mesothelium that surround organs, including:
 - Peritoneum that lines the abdominal cavity
 - Pericardium that surrounds the heart
 - Pleura that surround the lungs
 - · Periosteum, membrane that surrounds bone
 - The meninges that surround the brain: the dura mater, arachnoid mater, and the pia mater
- Skin, part of the integumentary system

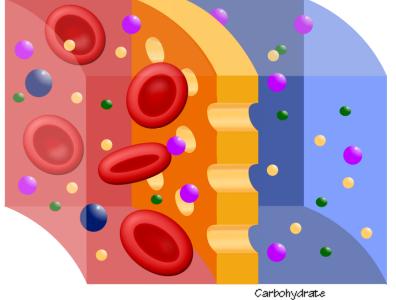
Membrane may also refer to:

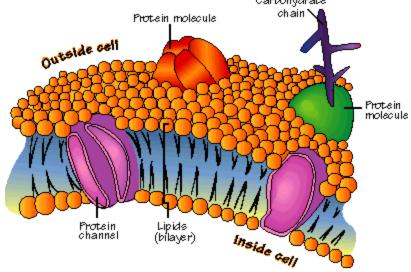
- A mechanical membrane, a thin, flat flexible part that can deform or vibrate when excited by an external force.
- Membrane keyboard
- Artificial, semipermeable membranes which are used to separate species in a fluid on the basis of size, charge or other characteristics. Such membranes are employed in a range of applications from water and wastewater treatment (see reverse osmosis, diffuser (sewage), landfill liners, nanofiltration, ultrafiltration and microfiltration) to hydrogen fuel cells (see proton exchange membrane).
- The Membranes an English post-punk band
- Membranes also refered to as branes in string theory





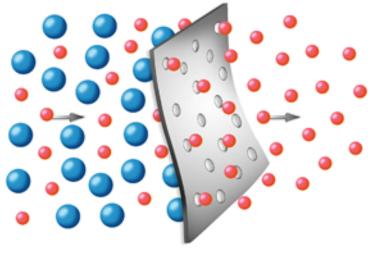
Dialysis/cell membrane

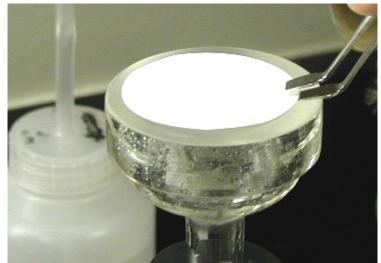




pore size uniformity is important

Fuel cell

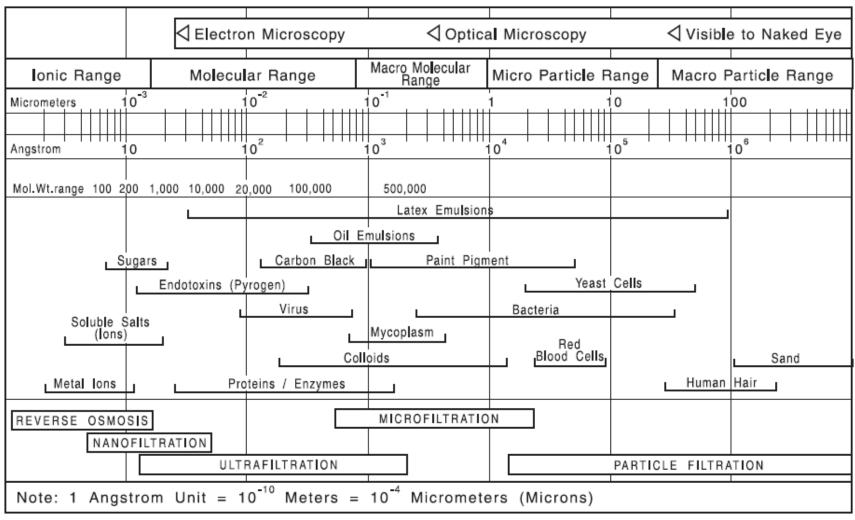




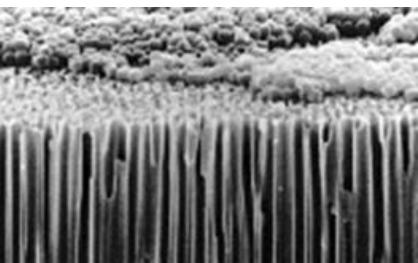
Disc filter

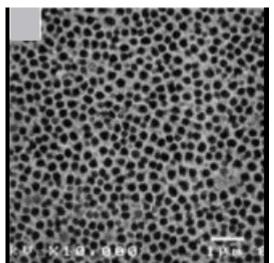
Regimes of membrane filtration



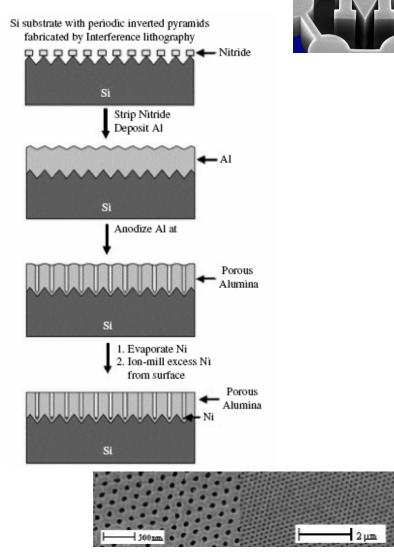


Nanoporous anodic alumina membranes





Whatman anopore membranes (not templated)



Template method: control size and spacing → regular arrays

Membrane filtration of nanoparticles by size exclusion (polymer membranes)



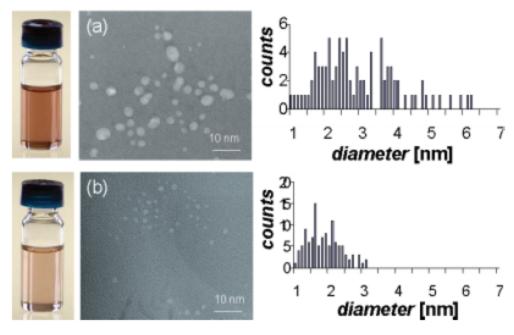
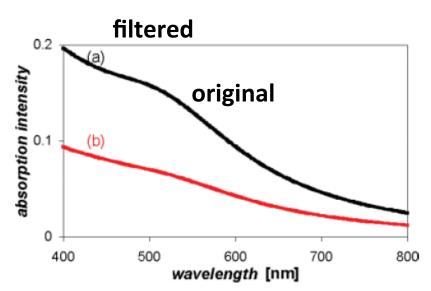
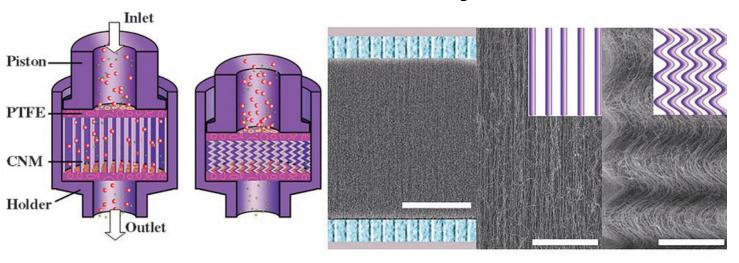


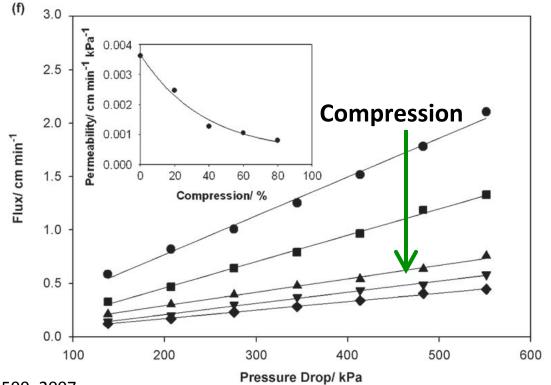
Figure 2. Optical absorption spectra and TEM images with metal core size statistics of nanoparticles prepared with 1:1 molar ratio of HS– C_{18} /Au in toluene. a) Feed solution (average size ~3.0±1.2 nm); b) solution permeated through PVDF-g-POEM-coated membrane with cutoff ~3.2 nm (average size ~1.9±0.5 nm).



CNT forests as mechanically tunable filters







A combination of methods usually seeks the desired final result (e.g., seed amplification)



Scheme 1. A Depiction of the Amplification Growth Process of a Carbon Nanotube

